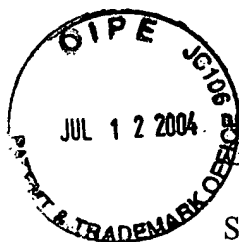


AF/2827
IFW



IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

GARY P. MORRISON ET AL.

Serial No. 10/034,827 (TI-31373)

Filed December 26, 2001 (As noted in Petition)

For: CHIP-SCALE PACKAGES STACKED ON FOLDED INTERCONNECTOR
FOR VERTICAL ASSEMBLY ON SUBSTRATES

Art Unit 2827

Examiner James M. Mitchell

Customer No. 23494

Director of the United States
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7-9-04

Jay M. Cantor, Reg. No. 19,906

AMENDMENT UNDER 37 CFR 1.16

Sir:

Responsive to the Office action dated June 16, 2004, please amend the above identified application as follows: